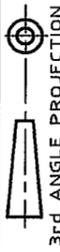


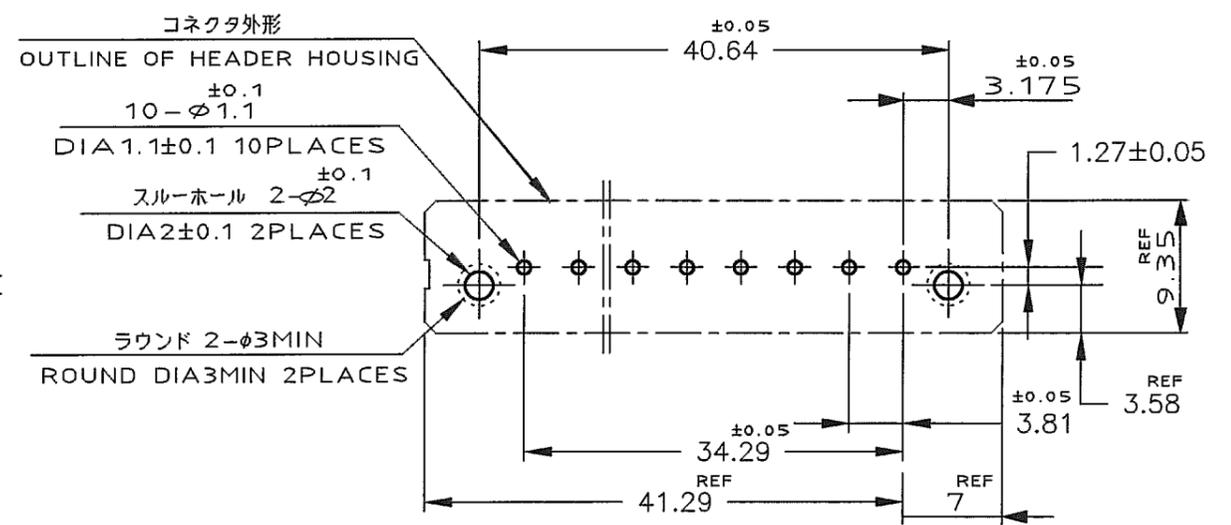
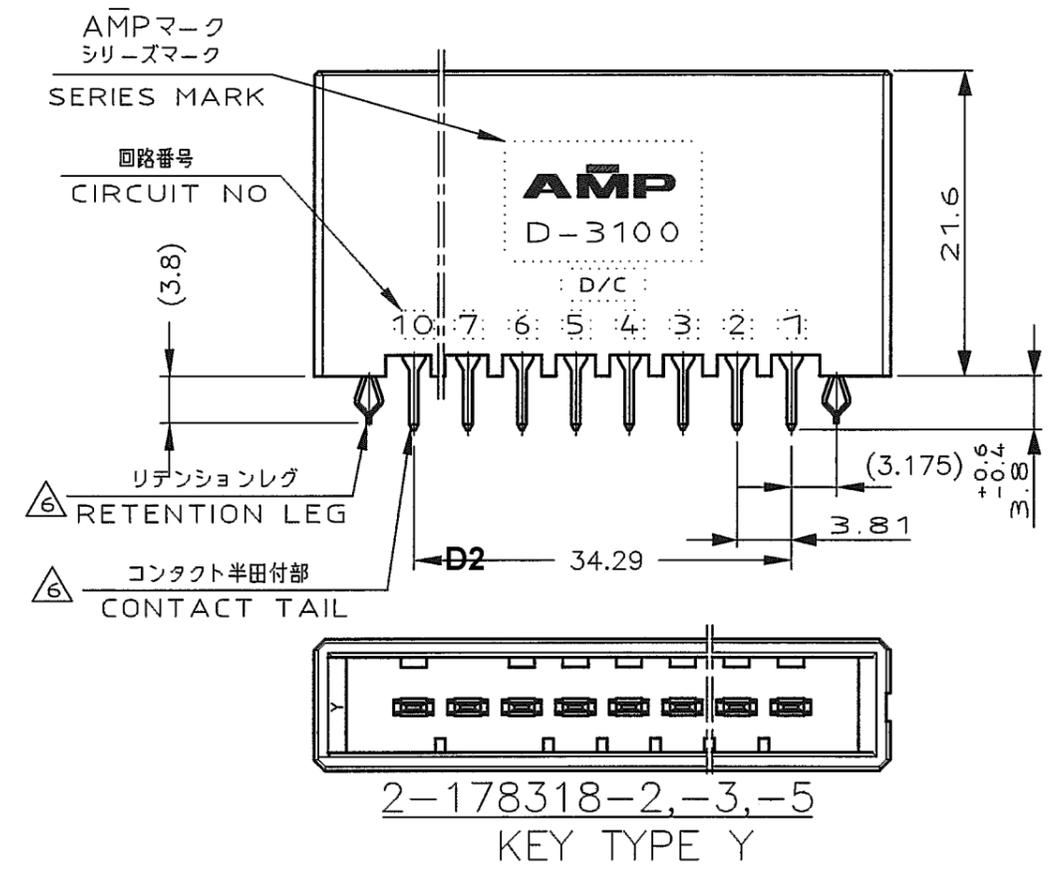
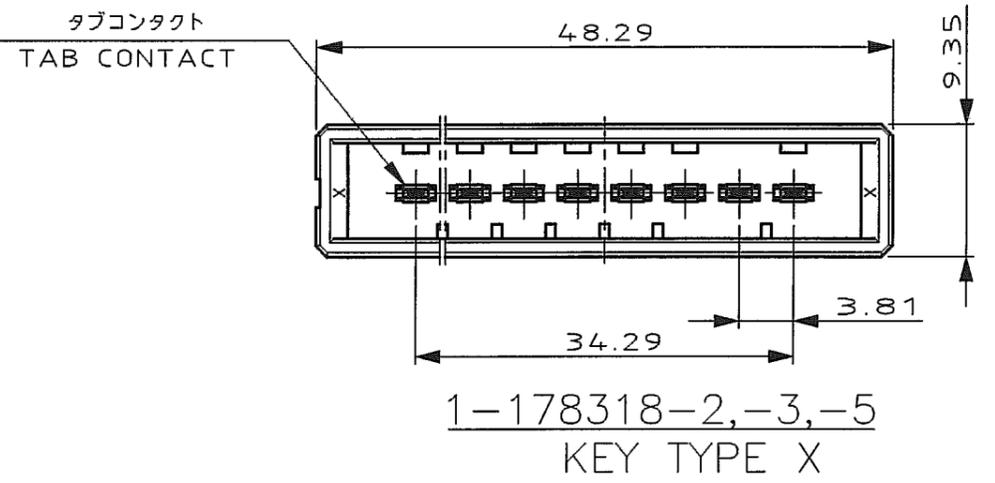
NUMBER 178318



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法

PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- 1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
- CONTACT: COPPER ALLOY
- RETENTION LEG: COPPER ALLOY
- △2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- △3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- △4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- △5. FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- △6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- △7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

注記

- 1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
- コンタクト: 銅合金
- リテンションレグ: 銅合金
- △2. めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
- △3. めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
- △4. めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
- △5. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- △6. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

Y	△6 △4	2-178318-5	OBSOLETE △
	△6 △3	2-178318-3	
	△6 △2	2-178318-2	
X	△6 △4	1-178318-5	
	△6 △3	1-178318-3	
	△6 △2	1-178318-2	
キーイング KEYING	FINISH	製品番号 PART NO.	

D2	REVISED PER ECO-11-005030	RK	HMR	24MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA	NAME	
mm (AWG -)		mmφ	10 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC 3100	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		
DR. Y.TANAKA 9 JUN 92	DE. Y.TANAKA 9 JUN 92	SCALE	REV.	SHEET
CHK. S.MANABE 22 JUN 92	APP. S.MANABE 22 JUN 92	2-1	D2	1 OF 1



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